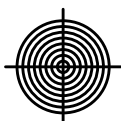
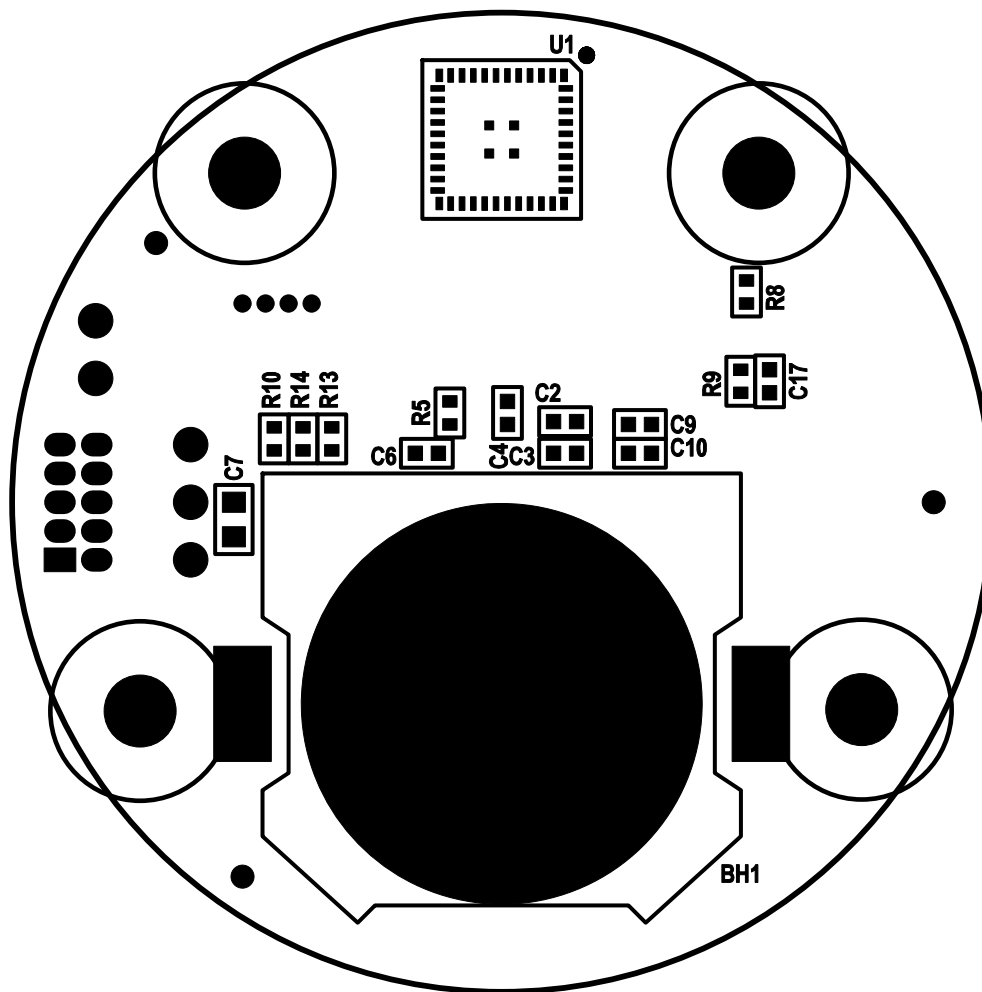
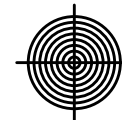
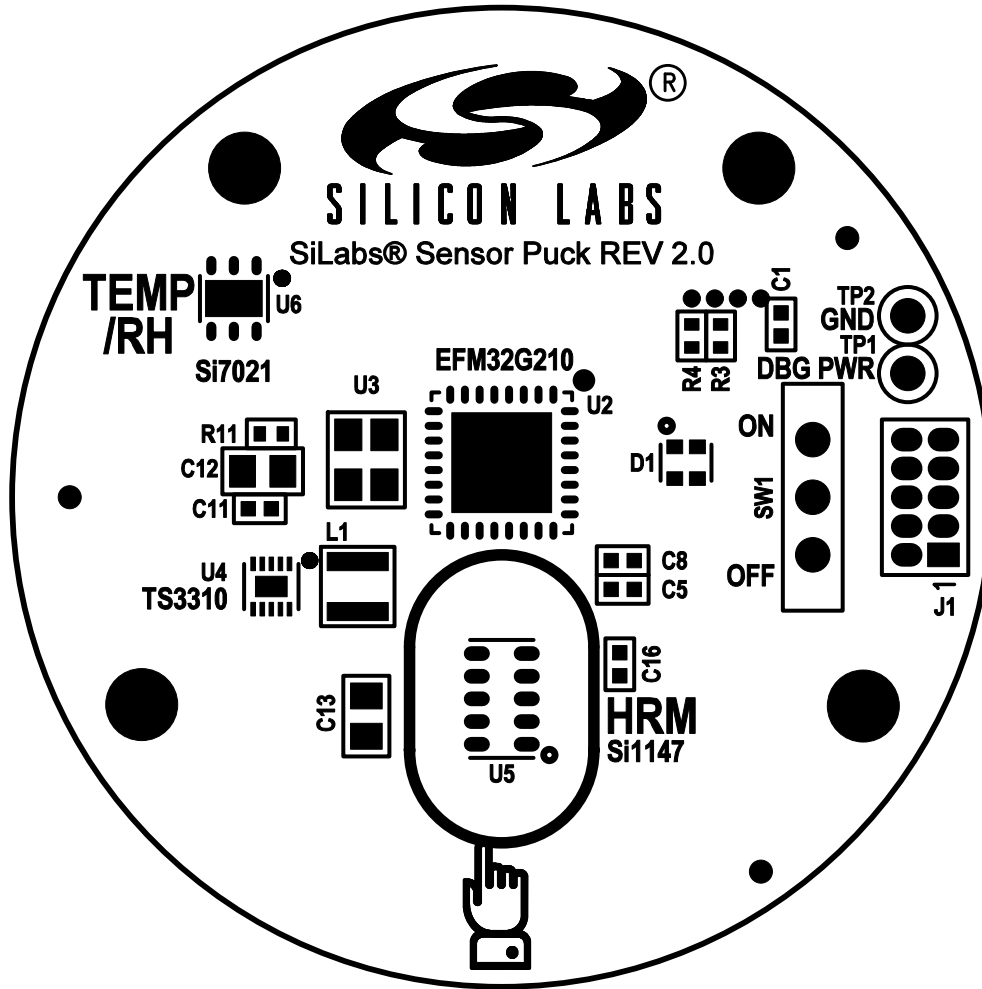
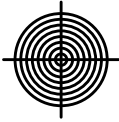


PRIMARY SILKSCREEN

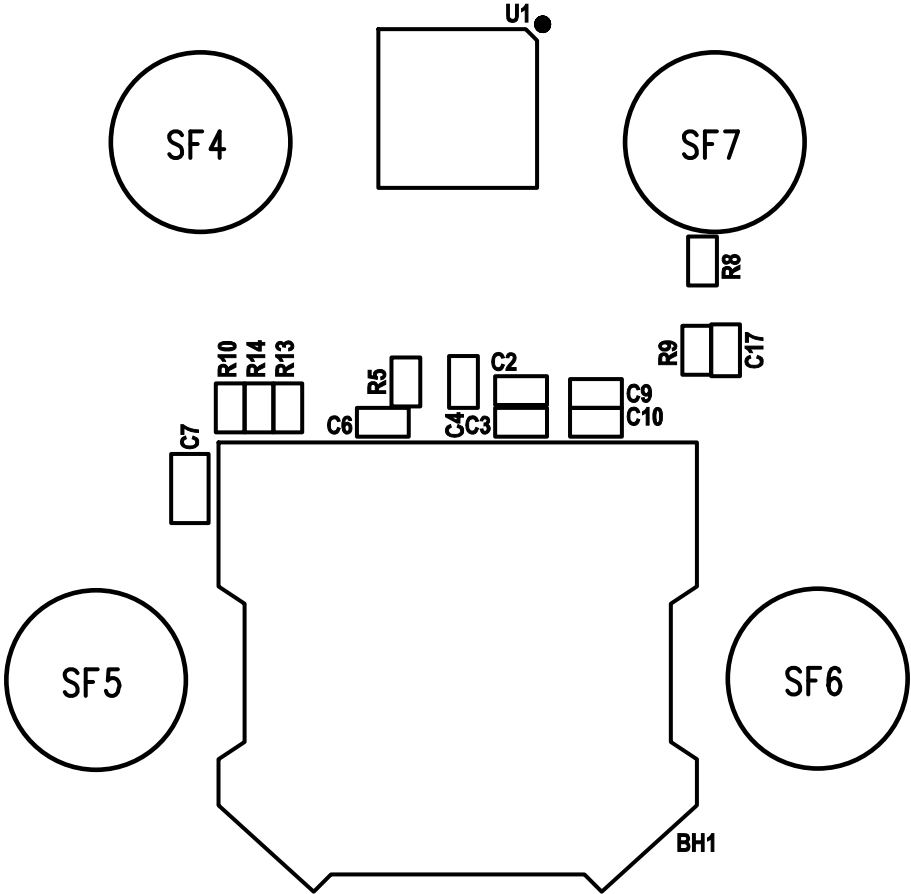


SECONDARY SILKSCREEN

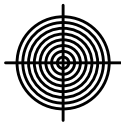
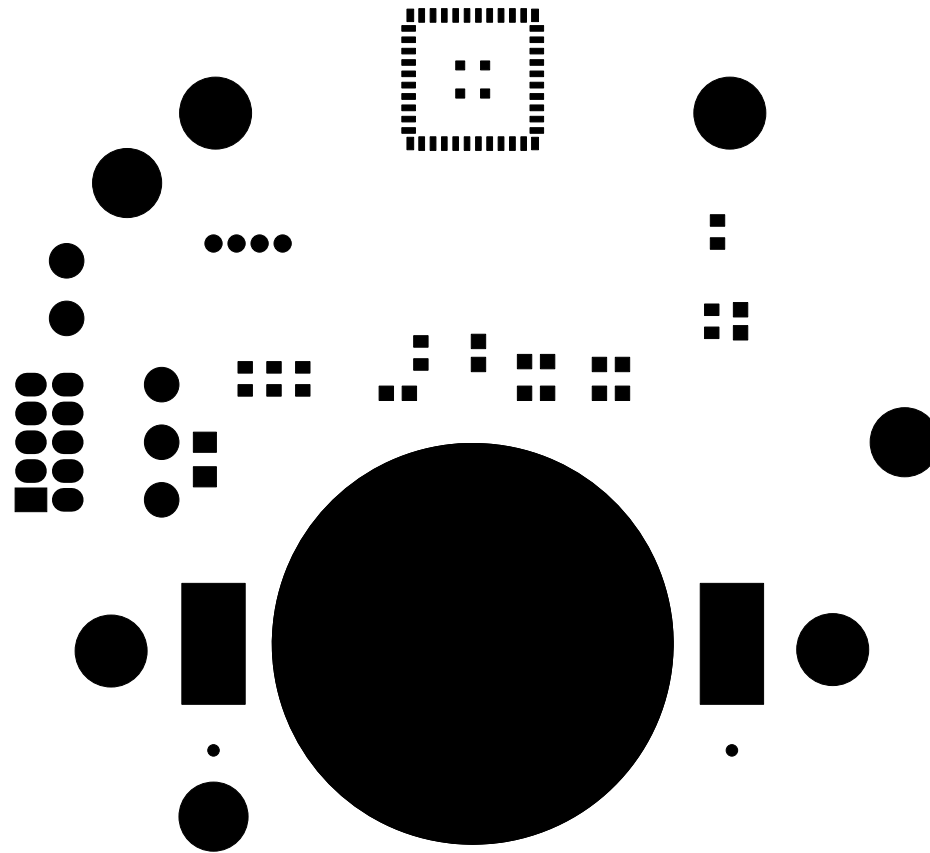
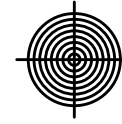
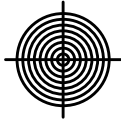




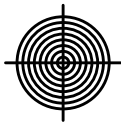
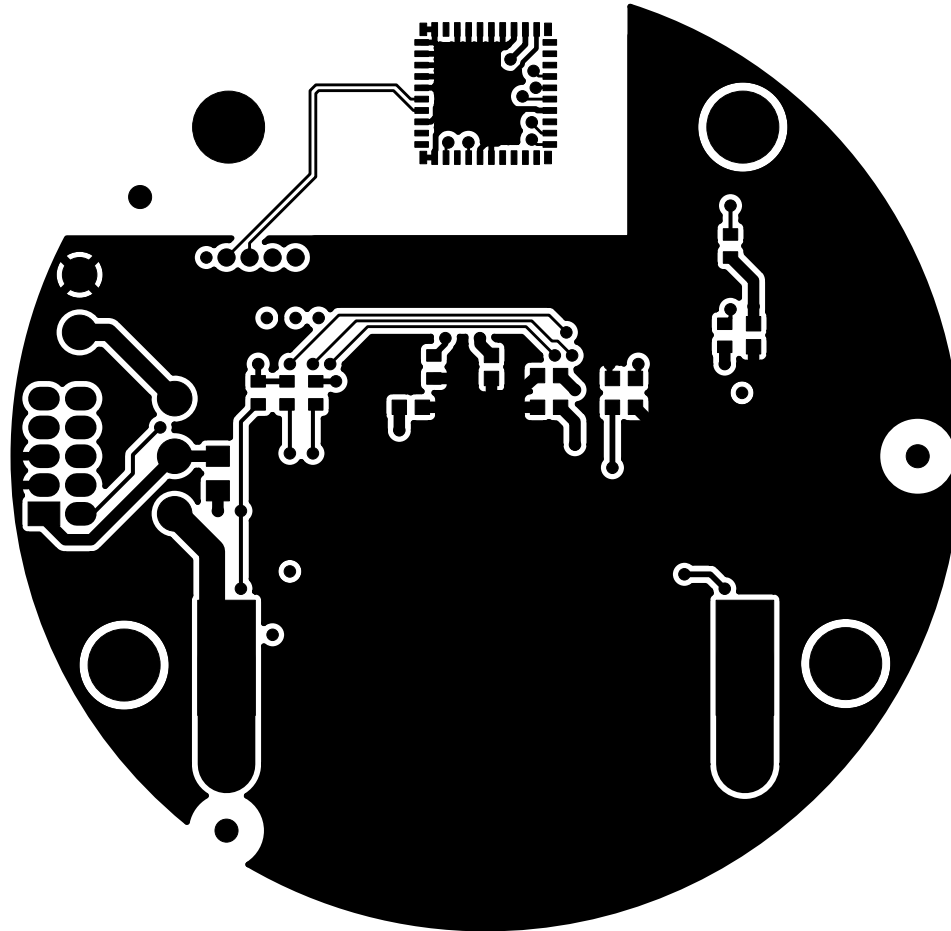
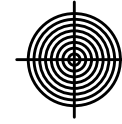
PRIMARY SILKSCREEN



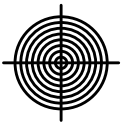
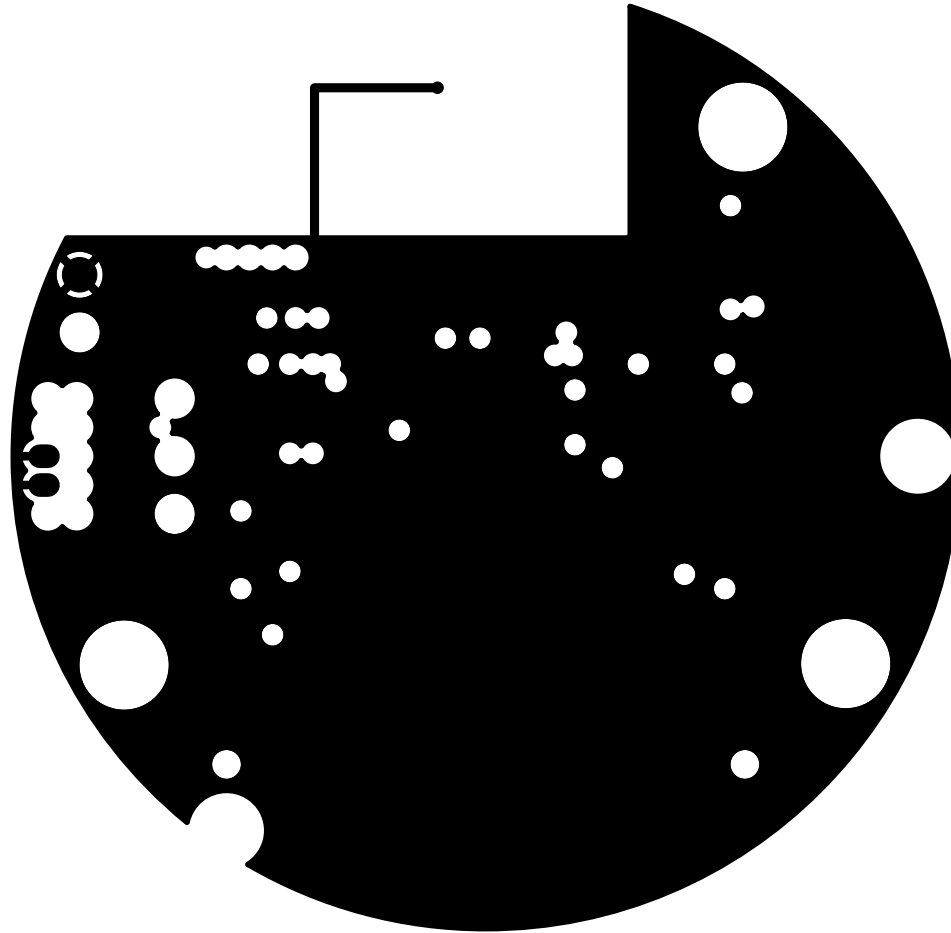
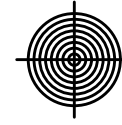
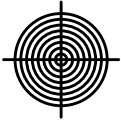
PRIMARY SOLDER MASK



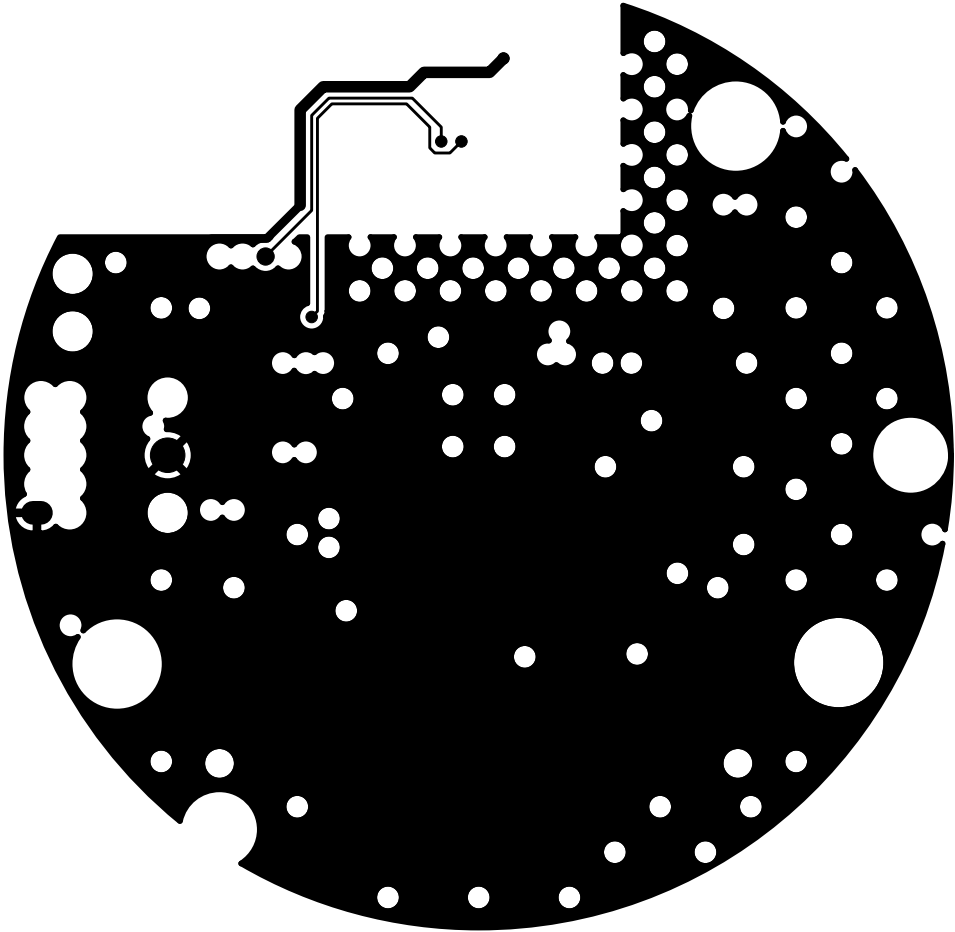
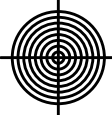
PRIMARY SIDE



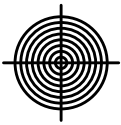
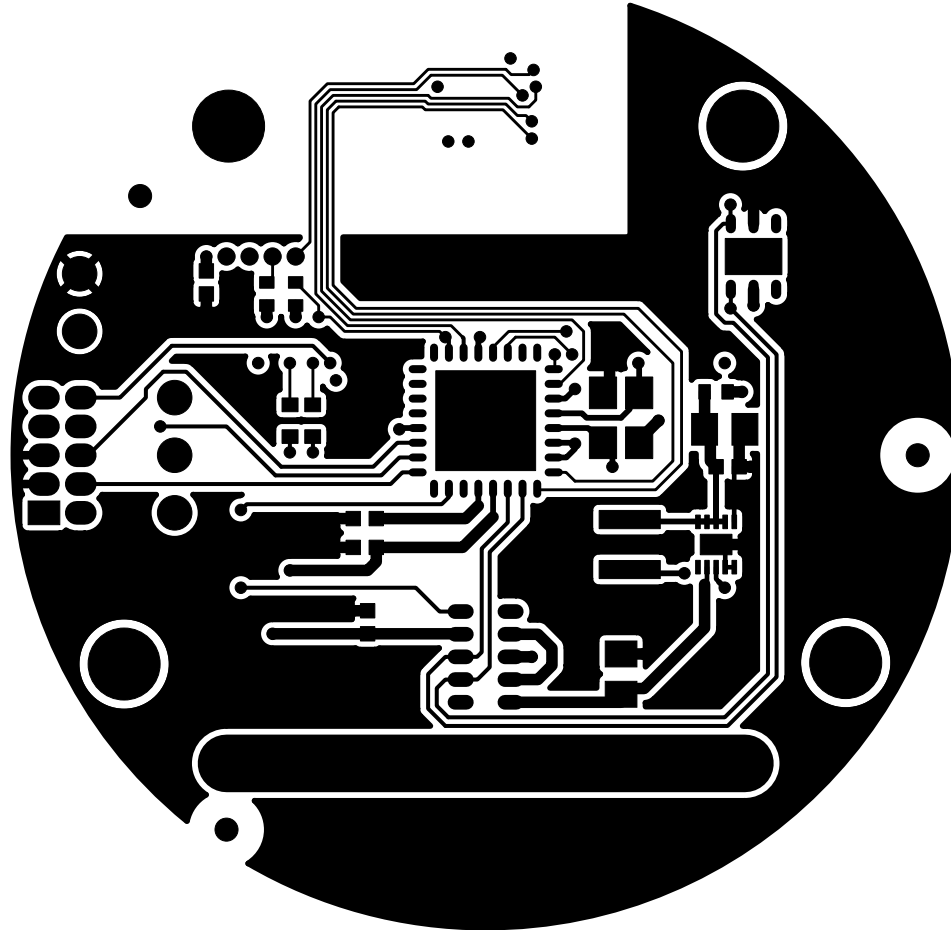
GROUND PLANE



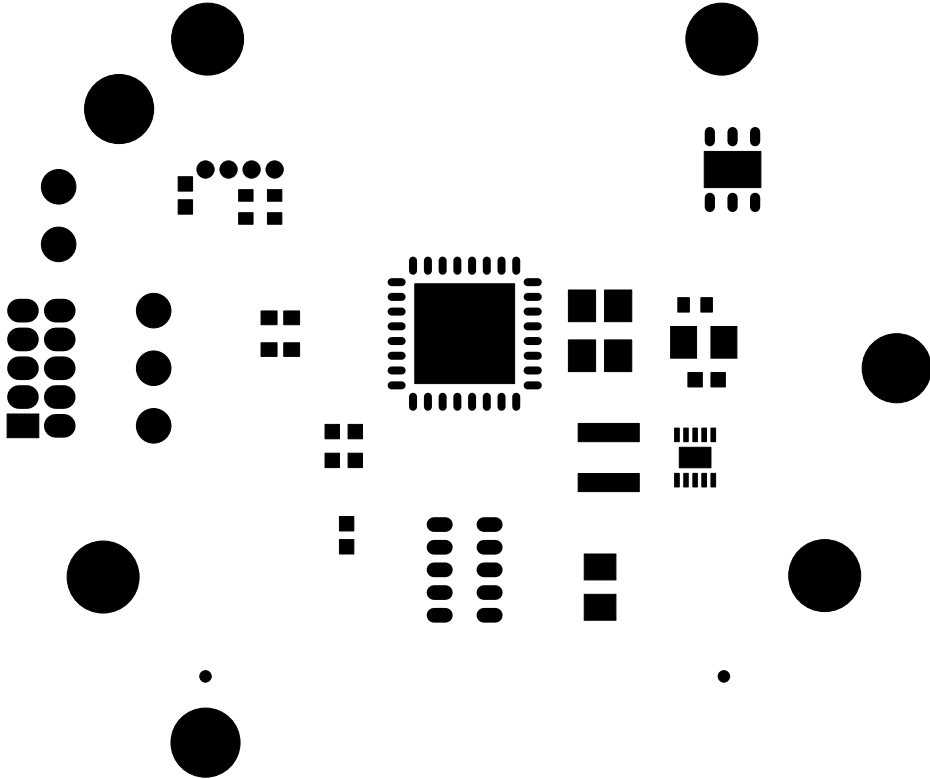
POWER PLANE



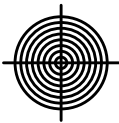
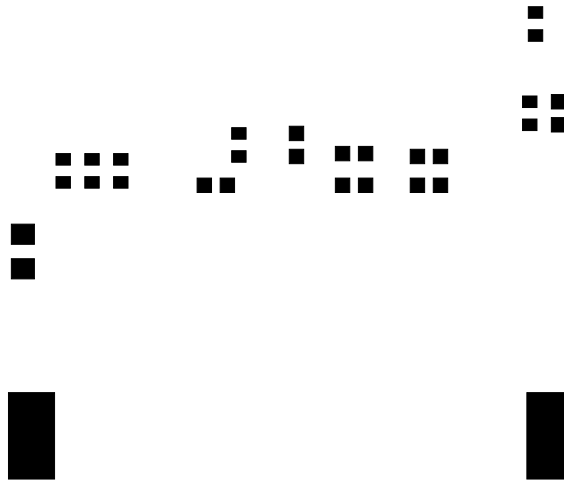
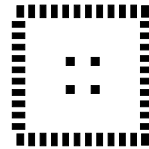
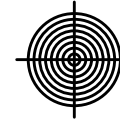
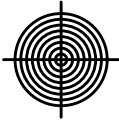
SECONDARY SIDE

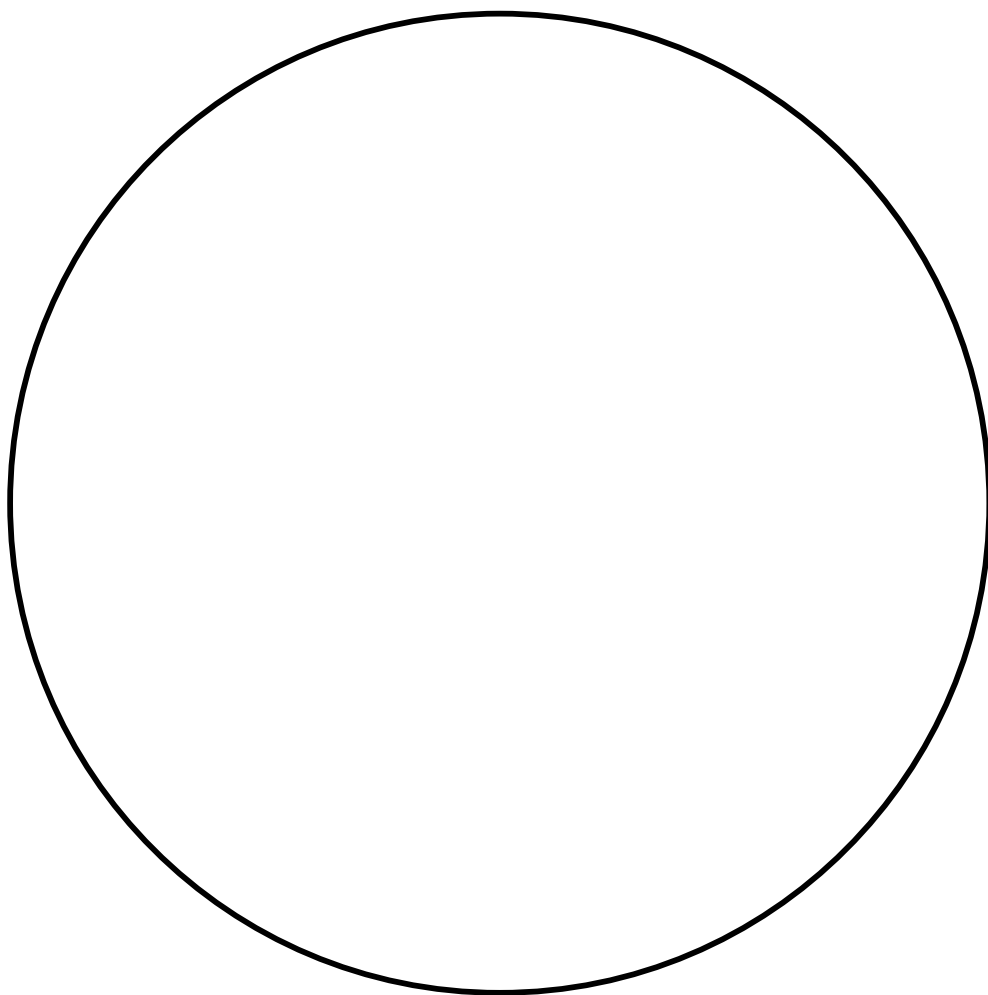


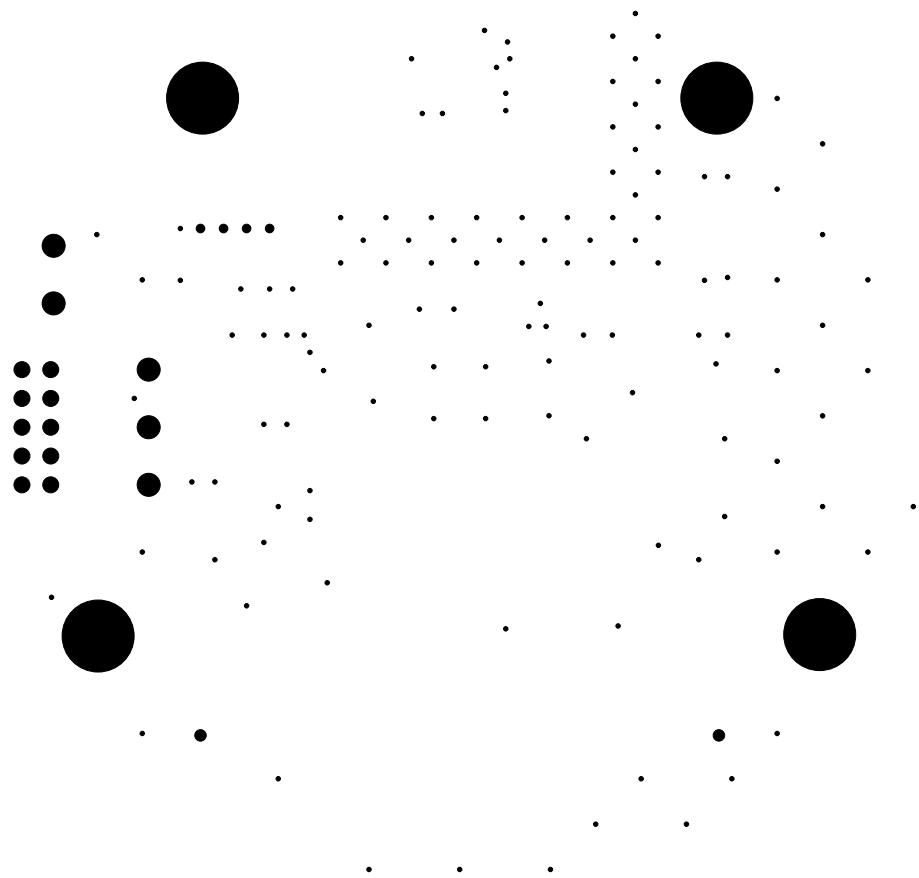
SECONDARY SOLDER MASK



PRIMARY SOLDER PASTE

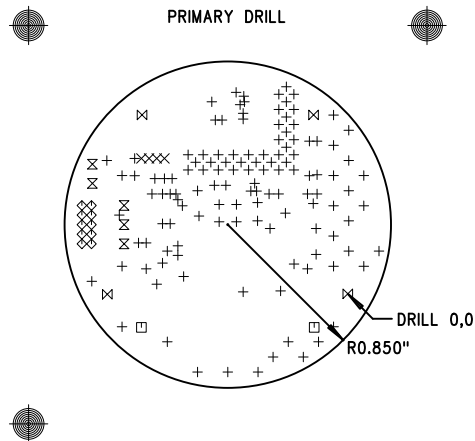






NOTES : UNLESS OTHERWISE SPECIFIED

1. MANUFACTURE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
2. END PRODUCT FEATURES SHALL NOT VARY MORE THAN 20% FROM ARTWORK ORIGINALS.
3. MATERIAL SHALL BE COPPER CLAD FR-4, NEMA GRADE PER IPC-4101/26, COLOR NATURAL.
4. COPPER WEIGHT SHALL BE 1.0 OZ./SQ. FT. BEFORE PLATING.
5. ALL PLATED THROUGH HOLES SHALL HAVE A MINIMUM OF 0.001" COPPER.
6. DRILL HOLE TOLERANCE AFTER PLATING SHALL BE ± 0.003 ".
7. MINIMUM ANNULAR RING SHALL BE 0.001".
8. MINIMUM ANNULAR RING AT EMERGENT CONDUCTORS SHALL BE 0.003".
9. FINAL PCB THICKNESS SHALL BE 0.062" $\pm 10\%$.
10. WARP/TWIST SHALL NOT EXCEED 1.0%
11. FINISH SHALL BE LPI, BLACK SMOBC, ENIG BOTH SIDES.
12. SILKSCREEN WITH NONCONDUCTIVE WHITE EPOXY INK.
13. REFERENCE ADDITIONAL FAB NOTES IN FILE README.TXT



LAYER STACKUP

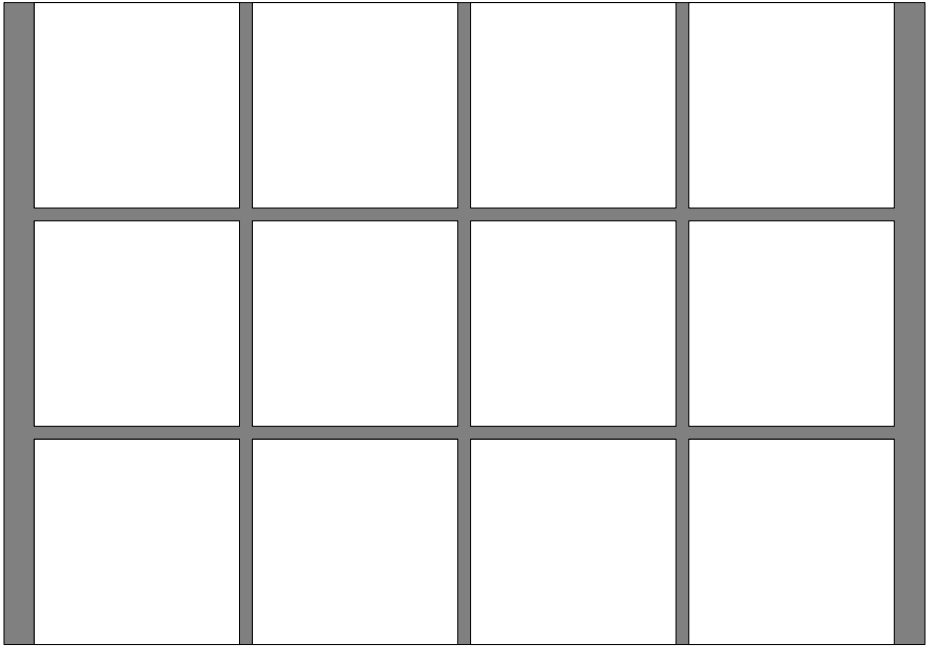
FILE NAMES

PRIMARY SILKSCREEN	PUCK_PSS.PHO
PRIMARY SOLDERMASK	PUCK_PSM.PHO
PRIMARY SIDE	PUCK_PRI.PHO
GROUND PLANE	PUCK_L02.PHO
POWER PLANE	PUCK_L03.PHO
SECONDARY SIDE	PUCK_SEC.PHO
SECONDARY SOLDERMASK	PUCK_SSM.PHO
SECONDARY SILKSCREEN	PUCK_SSS.PHO

SCALE: NONE

SIZE	QTY	SYM	PLT	TOOL	TOL
0.008	127	+	P	1	+0/-0.008
0.015	4	X	P	2	+0/-0.015
0.020	2	□	P	3	+/-0.003
0.028	10	◇	P	4	+/-0.003
0.040	5	⊗	P	5	+/-0.003
0.125	4	⊗	N	6	+/-0.003

UNLESS OTHERWISE SPECIFIED			THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION AND SHALL NOT BE DUPLICATED OR USED FOR ANY PURPOSE OTHER THAN THAT FOR WHICH PROVIDED OR DISCLOSED IN WHOLE OR IN PART, WITHOUT THE WRITTEN CONSENT OF SILICON LABORATORIES, INC..			COMPANY: 400 W Cesar Chavez AUSTIN, TX 78701 (512)416-8500 www.silabs.com		
DIMENSIONS ARE IN INCHES AND APPLY AFTER FINISH DIMENSIONS IN BRACKETS [] ARE IN MILLIMETERS INTERPRET DRAWING PER MIL-D-1000						NAME: Sensor Puck		
TOLERANCES			DESIGN			SIZE		
HOLE TOLERANCES PER 78027			JG					
DECIMALS .XX +/- .XXX +/-	ANGLES +/-	SURFACES MICROINCHES	LAYOUT			A		
PART TO BE FREE OF BURRS			30SEP2014					
BREAK EDGES			30SEP2014			FABRICATION DRAWING		
BEND RADIUS MAX	BEND RELIEF MAX	SURFACES MAX	DO NOT SCALE DRAWING					



Sensor_Puck REV 2.0

Size:
Array: 7.6 x 5.3
Part: 1.7 x 1.7

Parts On Array:
12 Parts

Matrix:
4 x 3

Spacing:
0.1 x 0.1

Array Borders:
Left: 0.25 Right: 0.25
Top: 0.0 Bottom: 0.0

Notes:

Please add 4, 0.125" NP tooling holes located 0.125" from tab corners and 3, 40/120 fiduials to each side of array located 0.25" from tooling holes.